



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20180820002
Datasheet for DRV5013
Information Only**

Date: August 21, 2018
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DRV5013ADQDBZR	null
DRV5013ADQDBZT	null
DRV5013ADQLPG	null
DRV5013AGQLPG	null
DRV5013FAQDBZR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180820002	PCN Date:	August 21, 2018
Title:	Datasheet for DRV5013		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



DRV5013

SLIS150I – MARCH 2014 – REVISED AUGUST 2018

Changes from Revision H (September 2016) to Revision I	Page
• Changed <i>Power Supply Recommendations</i> section	19

The datasheet number will be changing.

Device Family	Change From:	Change To:
DRV5013	SLIS150H	SLIS150I

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/DRV5013>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

DRV5013ADQDBZR	DRV5013ADQDBZT	DRV5013ADQLPG	DRV5013ADQLPGM
DRV5013AGQDBZR	DRV5013AGQDBZT	DRV5013AGQLPG	DRV5013AGQLPGM
DRV5013BCQDBZR	DRV5013BCQDBZT	DRV5013BCQLPG	DRV5013BCQLPGM
DRV5013FAQDBZR			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com